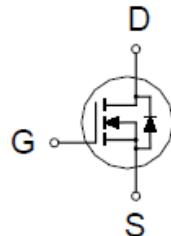
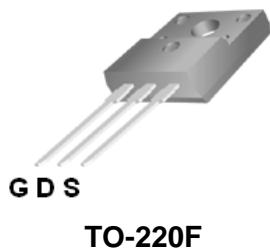


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PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
100V	26.8mΩ @ $V_{GS} = 10V$	24A



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ C$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS	SYMBOL	LIMITS	UNITS
Drain-Source Voltage	V_{DS}	100	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current $T_C = 25^\circ C$	I_D	24	A
		15	
Pulsed Drain Current ¹	I_{DM}	70	A
Avalanche Current	I_{AS}	11.7	
Avalanche Energy	E_{AS}	6.9	mJ
Power Dissipation $T_C = 25^\circ C$	P_D	37.9	W
		15	
Junction & Storage Temperature Range	T_J, T_{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$	3.3	62.5	°C / W
Junction-to-Ambient	$R_{\theta JA}$			

¹Pulse width limited by maximum junction temperature.

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ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)

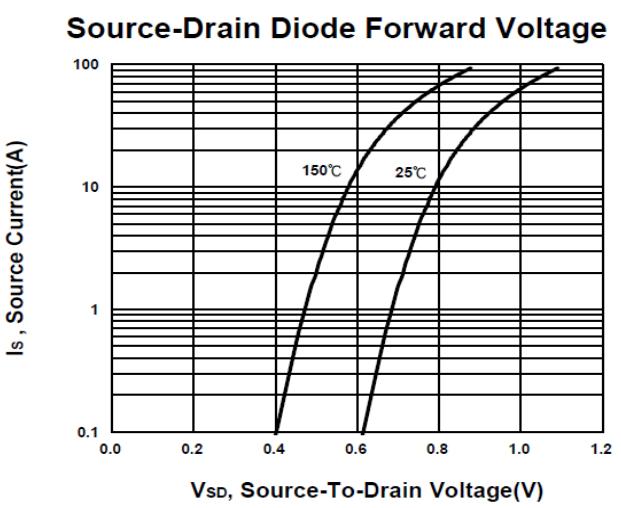
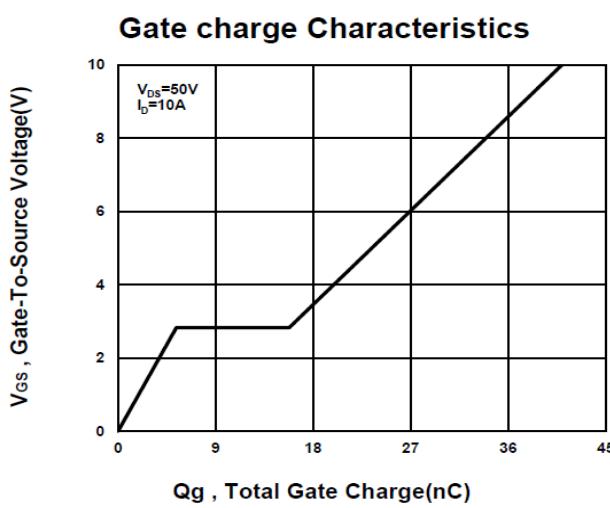
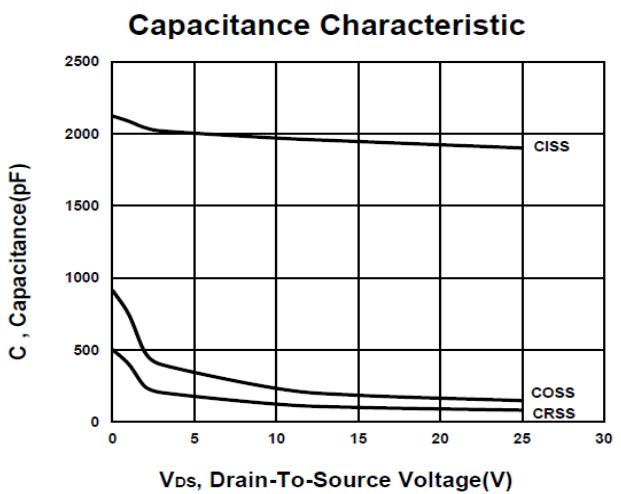
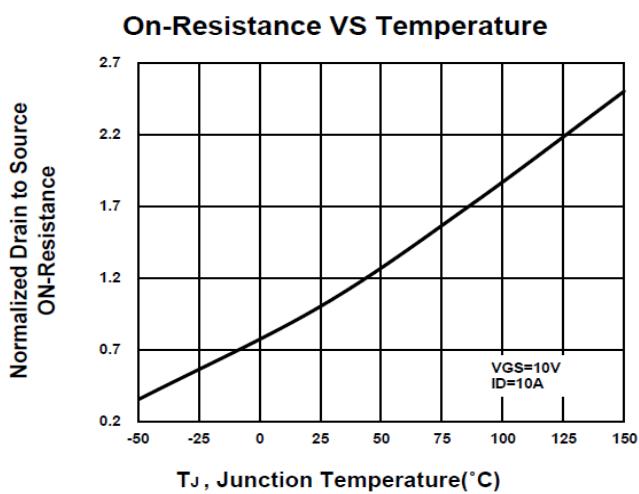
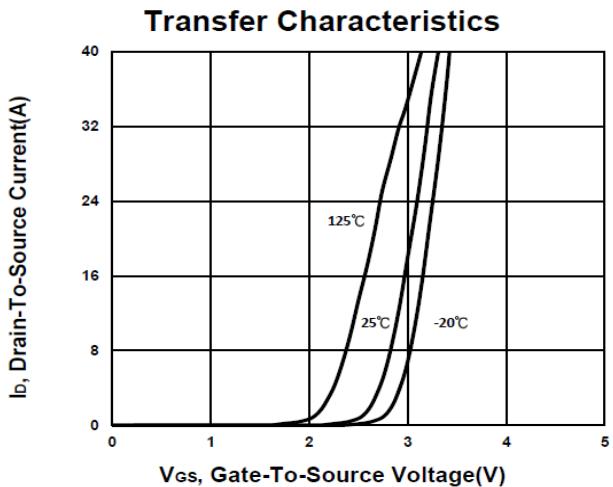
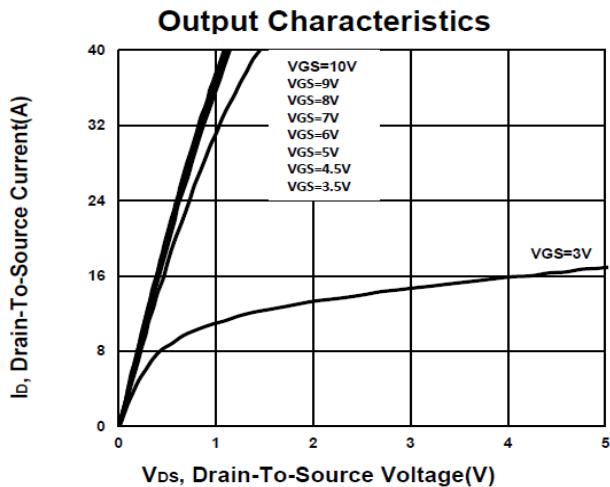
PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNITS
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	100			V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	1.3	1.8	2.3	
Gate-Body Leakage	I_{GSS}	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 20\text{V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 80\text{V}, V_{\text{GS}} = 0\text{V}$			1	μA
		$V_{\text{DS}} = 80\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 125^\circ\text{C}$			10	
Drain-Source On-State Resistance ¹	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}} = 10\text{V}, I_D = 10\text{A}$		19.3	26.8	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}, I_D = 10\text{A}$		23.3	35	
Forward Transconductance ¹	g_{fs}	$V_{\text{DS}} = 5\text{V}, I_D = 10\text{A}$		50		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 25\text{V}, f = 1\text{MHz}$		1900		pF
Output Capacitance	C_{oss}			149		
Reverse Transfer Capacitance	C_{rss}			92		
Gate Resistance	R_g	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 0\text{V}, f = 1\text{MHz}$		0.8		Ω
Total Gate Charge ²	$Q_{\text{g}}(V_{\text{GS}} = 10\text{V})$	$V_{\text{DS}} = 50\text{V}, I_D = 10\text{A}$		41.5		nC
	$Q_{\text{g}}(V_{\text{GS}} = 4.5\text{V})$			22.4		
Gate-Source Charge ²	Q_{gs}			6		
Gate-Drain Charge ²	Q_{gd}			11.6		
Turn-On Delay Time ²	$t_{\text{d(on)}}$	$V_{\text{DS}} = 50\text{V}, I_D \geq 10\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 6\Omega$		16		nS
Rise Time ²	t_r			45		
Turn-Off Delay Time ²	$t_{\text{d(off)}}$			47		
Fall Time ²	t_f			38		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_J = 25^\circ\text{C}$)						
Continuous Current	I_S				24	A
Forward Voltage ¹	V_{SD}	$I_F = 10\text{A}, V_{\text{GS}} = 0\text{V}$			1.2	V
Diode Reverse Recovery Time	t_{rr}	$I_F = 10\text{A}, dI/dt = 100\text{A}/\mu\text{s}$		32		nS
Diode Reverse Recovery Charge	Q_{rr}			36		uC

¹Pulse test : Pulse Width $\leq 300\ \mu\text{sec}$, Duty Cycle $\leq 2\%$.

²Independent of operating temperature.

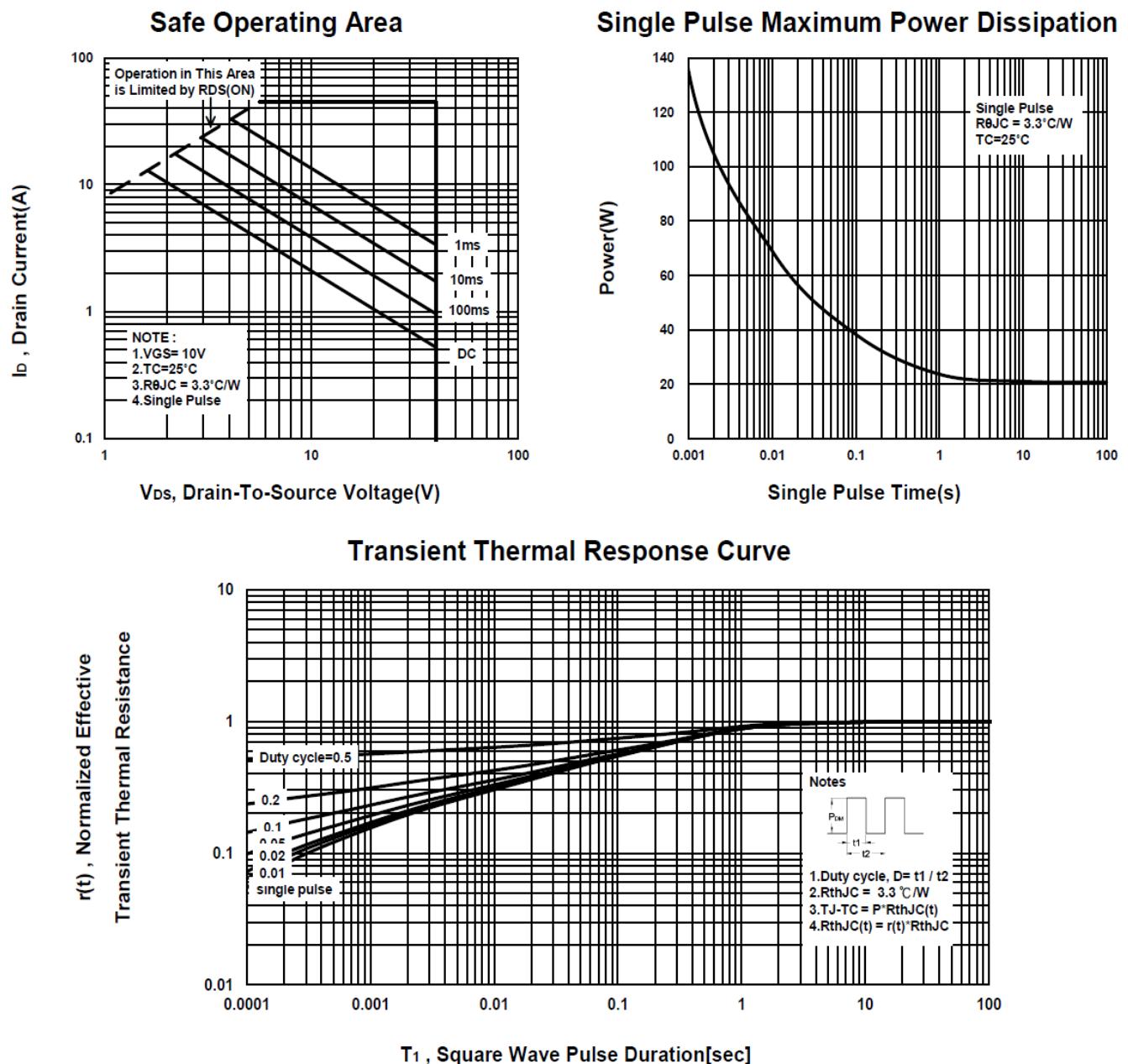
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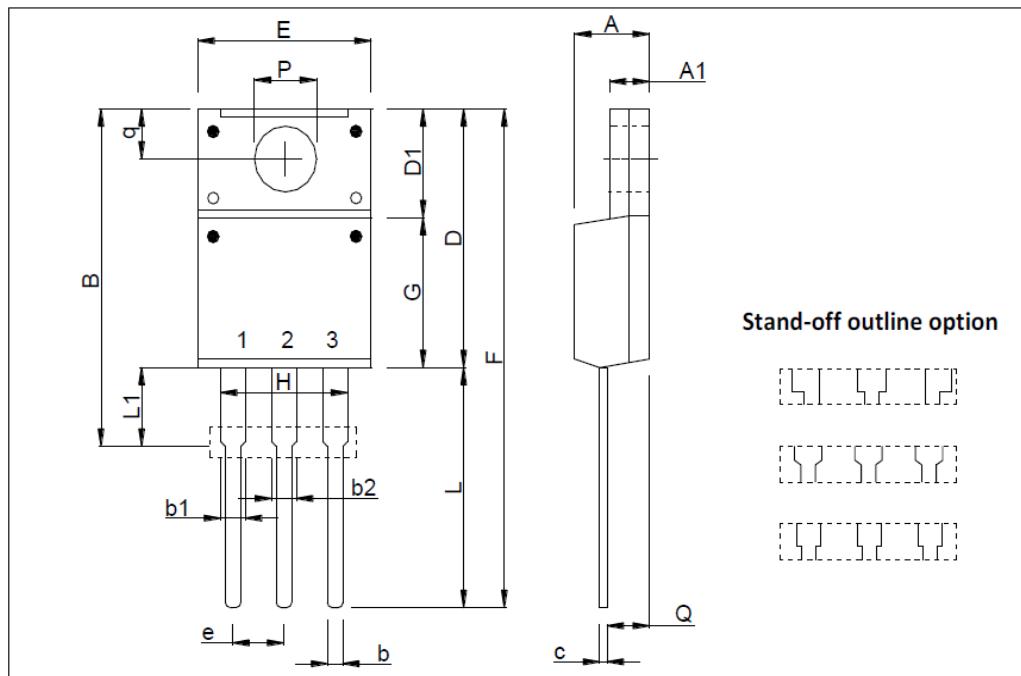
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Package Dimension

TO-220F (3-Lead) MECHANICAL DATA

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.4		4.93	e	2.34		2.74
A1	2.34		3.1	F	27.2		30.6
B	18.8		20	G	7.7		9.39
b	0.65		1	H	6.18		6.82
b1	0.93		1.6	L	12.7		14.2
b2	0.95		1.6	L1	2.88		3.7
c	0.4		1	P	2.98		3.7
D	13.5		16.4	Q	2.3		2.96
D1	6.48		6.95	q	3.1		3.8
E	9.8		10.4				

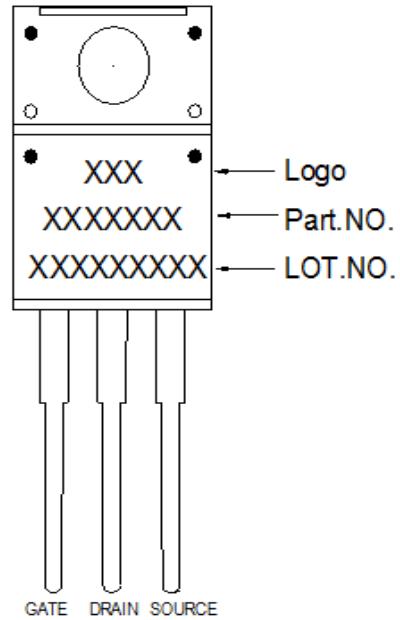


*因各家封装模具不同而外观略有差异，不影响电性及Layout。

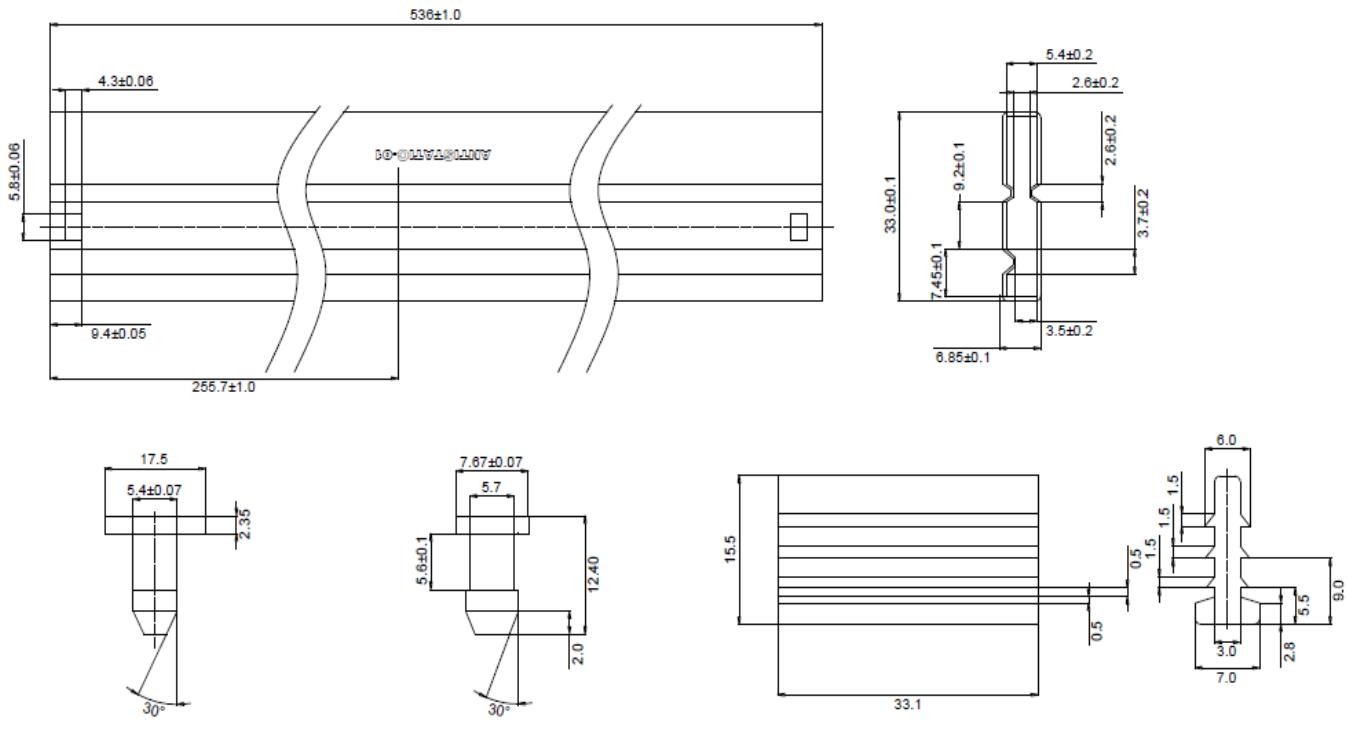
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N-Channel Enhancement Mode MOSFET

A. Marking Information



B. Tape&Reel Information: 50pcs/Tube(2000pcs/Box)

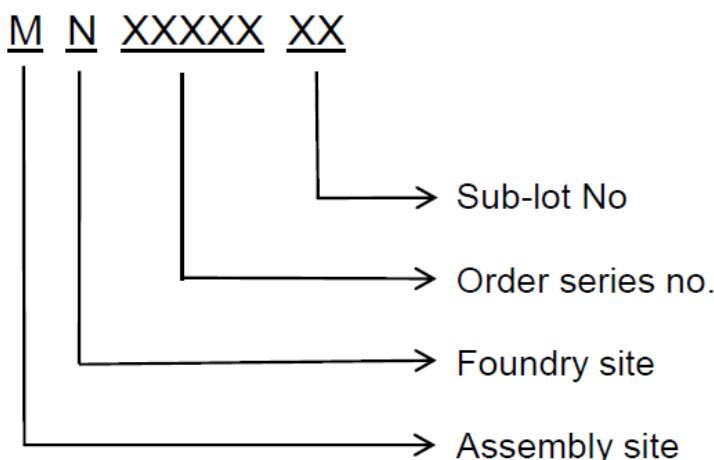


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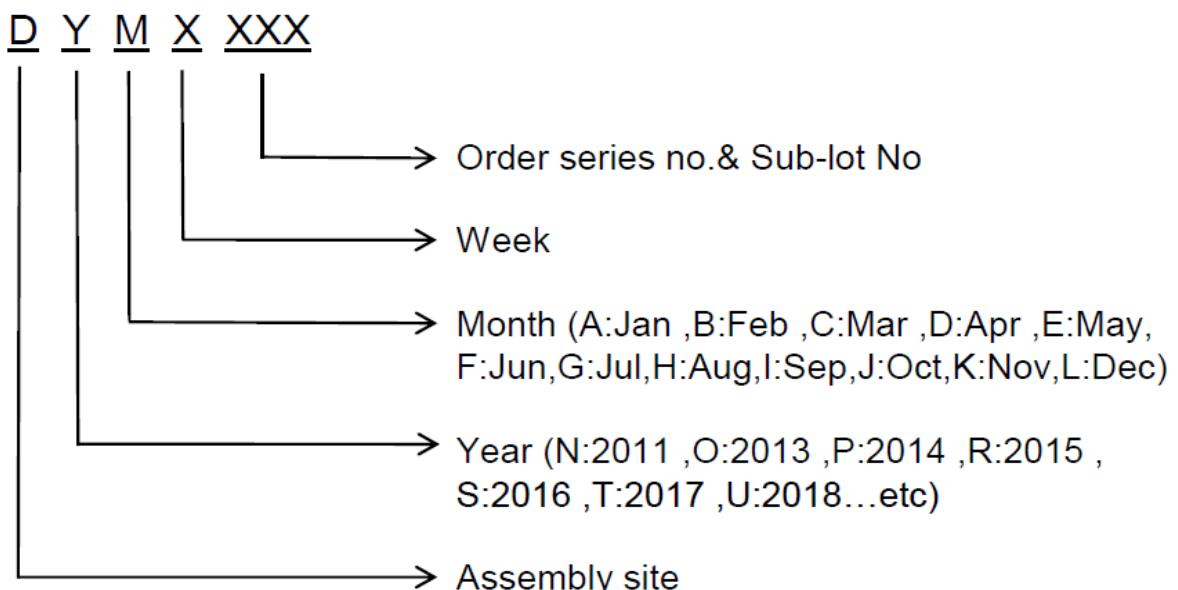
N-Channel Enhancement Mode MOSFET

C. Lot No.&Date Code rule

1. Lot No.



2. Date Code



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D.Label rule

标签内容(Label content)



1	Label Size	30 * 90 mm			
2	Font style	Times New Roman or Arial (或可区分英文“0”和数字“0”，“G”和“Q”的字型即可)			
3	U-NIKC	Height: 4 mm			
4	Package	Height: 2 mm			
5	Date	Height: 2 mm Shipping date: YYYY/MM/DD, ex. 2008/09/12			
6	Device	Height: 3 mm (Max: 16 Digit)			
7	Lot	Height: 3 mm (Max: 9 Digit) Sub lot			
8	D/C	Height: 3 mm (Max: 7 Digit)			
9	QTY	Height: 3 mm (Max: 6 Digit) Thousand mark is no needed			
10	RoHS label	 long axis: 12 mm minor axis: 6 mm bottom color: White Font color: Black Font style: Arial			
11	Halogen Free label	 Diameter: 10 mm bottom color: Green Font color: Black Font style: Arial			
12	Scan information	Device / Lot / D/C / QTY , Insert “ / ” between every parts. for example: P3055LDG/G12345601/GGG2301/2000 DPI (Dots per inch): Over 300 dpi Code : Code 128 Height: 6 mm at least			